

IAR Setup for the DRV2605EVM-BT Firmware

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Tools Needed:

1. **DRV2605EVM-BT firmware source** – Available under the software section of the DRV2605EVM-BT product folder: <http://www.ti.com/tool/drv2605evm-bt>
2. TI-BLE Stack: <http://www.ti.com/tool/ble-stack>
3. IAR Embedded Workbench for 8051: www.iar.com/Products/IAR-Embedded-Workbench/8051/
4. Admin privileges on a PC.
5. CC-Debugger: <http://www.ti.com/tool/cc-debugger>
6. TC2050-IDC-NL 10-Pin No-Legs Cable with Ribbon connector: <http://www.tag-connect.com/TC2050-IDC-NL>

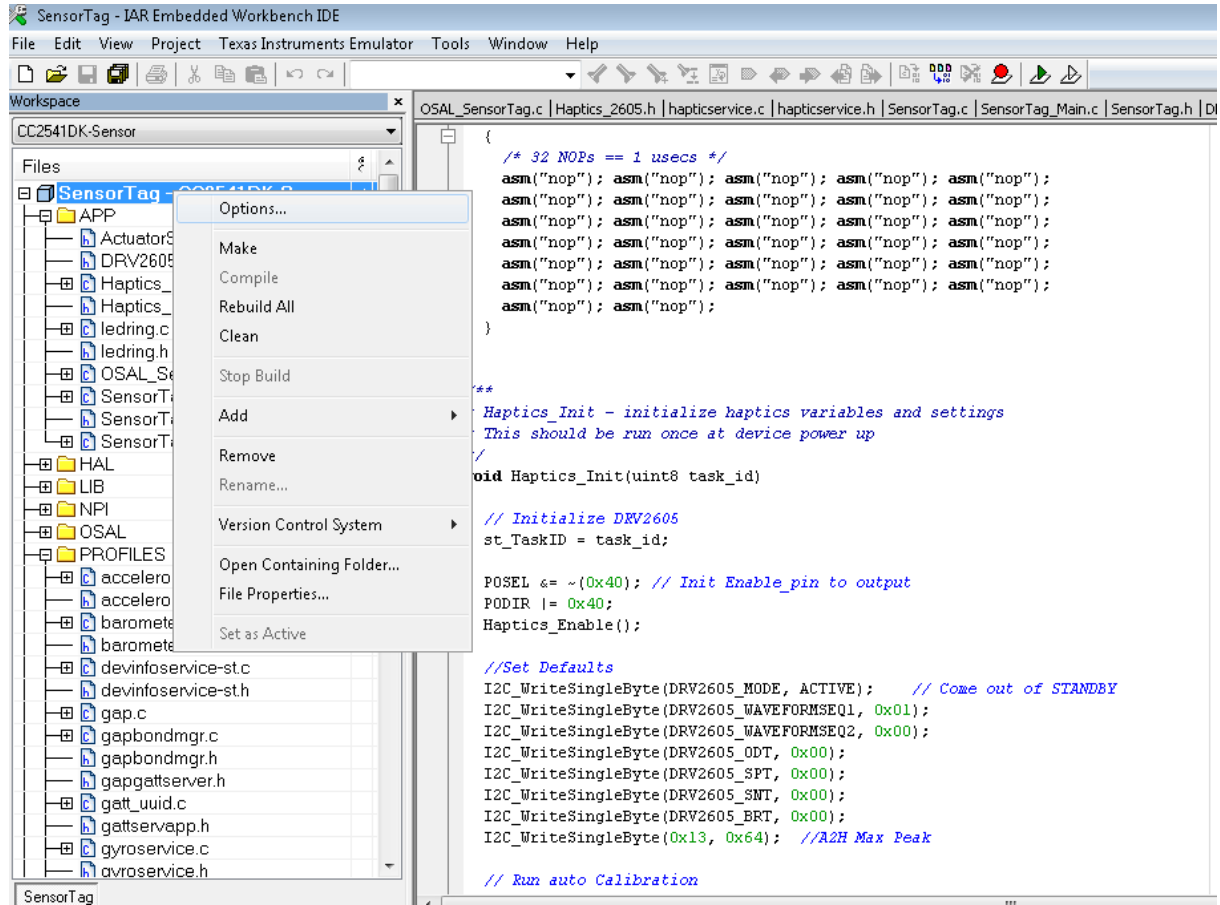
Steps:

1. Login as administrator and install IAR Embedded Workbench.
2. Download and unzip the TI-BLE stack installer. Install the BLE stack.
3. This creates the following folder structure where all the projects will be located:
C:\Texas Instruments\BLE-CC254x-1.4.0\Projects\ble
4. Unzip the DRV2605EVM-BT Firmware Sourcev1.0 on your computer.
5. Copy the **DRV2605EVM-BT_Firmware folder** and paste it under the **Projects\ble** location from Step 3.
6. Inside the DRV2605EVM-BT_Firmware directory, navigate to the **CC2541DB** directory. Open the SensorTag.eww workspace with IAR.
7. This opens all the project files associated with the DRV2605EVM-BT.
8. Build the project.

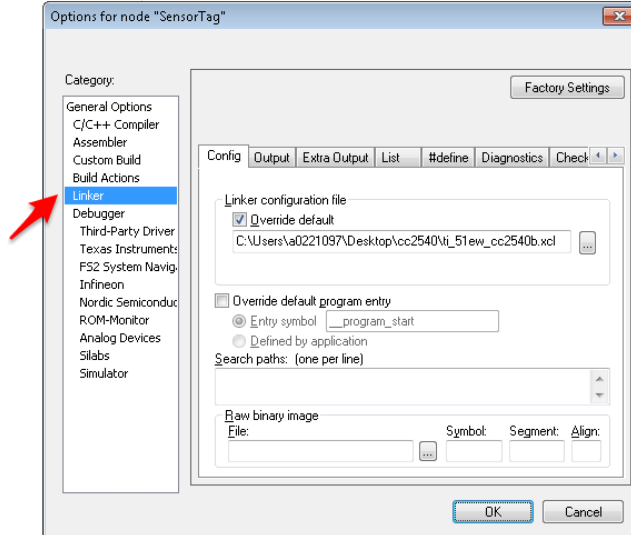
Troubleshooting:

1. IAR 8.3 has shown some issues with projects created in older versions of IAR.
2. If you observe build errors with this project, correct by using the next steps.
3. Unzip the **cc2540_specific_xcls.zip** folder included with the DRV2605EVM-BT FirmwareSourcev1.0.

4. Right click the project within IAR and select **Options**.



5. Navigate to Linker and under the linker configuration file, select **Override default** and select the **"ti_51ew_cc2540b.xcl"** file from the previously unzipped cc4540 folder.



6. Clean and Rebuild the project.

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